

### General Description

The MDIS5N40 uses advanced Magnachip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

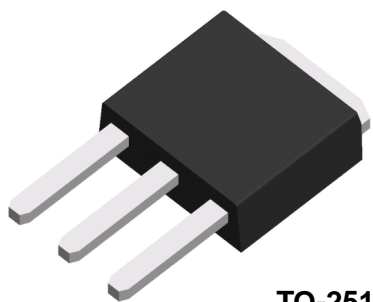
MDIS5N40 is suitable device for SMPS, HID and general purpose applications.

### Features

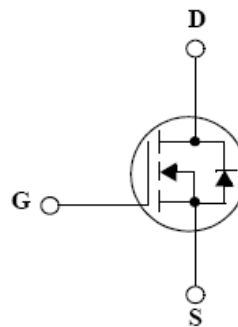
- $V_{DS} = 400V$
  - $I_D = 3.4A$
  - $R_{DS(ON)} \leq 1.6\Omega$
- @  $V_{GS} = 10V$   
@  $V_{GS} = 10V$

### Applications

- Power Supply
- PFC
- Ballast



**TO-251-VS  
(IPAK-VS)**



### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Drain-Source Voltage	$V_{DSS}$	400	V	
Gate-Source Voltage	$V_{GSS}$	±30	V	
Continuous Drain Current	$I_D$	$T_C=25^\circ C$	3.4	A
		$T_C=100^\circ C$	2.15	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	13.6	A	
Power Dissipation	$P_D$	$T_C=25^\circ C$	45	W
		Derate above 25 °C	0.36	W/°C
Peak Diode Recovery dv/dt <sup>(3)</sup>	Dv/dt	4.5	V/ns	
Repetitive Pulse Avalanche Energy <sup>(1)</sup>	$E_{AR}$	4.5	mJ	
Single Pulse Avalanche Energy <sup>(4)</sup>	$E_{AS}$	170	mJ	
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~150	°C	

### Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient <sup>(1)</sup>	$R_{\theta JA}$	110	°C/W
Thermal Resistance, Junction-to-Case <sup>(1)</sup>	$R_{\theta JC}$	2.75	

## Ordering Information

Part Number	Temp. Range	Package	Packing	RoHS Status
MDIS5N40TH	-55~150°C	TO-251-VS (IPAK-VS)	Tube	Halogen Free

## Electrical Characteristics (Ta =25°C)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	400	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	3.0	-	5.0	
Drain Cut-Off Current	$I_{DSS}$	$V_{DS} = 400V, V_{GS} = 0V$	-	-	1	$\mu A$
Gate Leakage Current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	100	nA
Drain-Source ON Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 1.7A$		1.2	1.6	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 30V, I_D = 1.7A$	-	2.0	-	S
<b>Dynamic Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 320V, I_D = 3.4A, V_{GS} = 10V$	-	9		nC
Gate-Source Charge	$Q_{gs}$		-	2.5		
Gate-Drain Charge	$Q_{gd}$		-	4		
Input Capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	-	290		pF
Reverse Transfer Capacitance	$C_{rss}$		-	3		
Output Capacitance	$C_{oss}$		-	46		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10V, V_{DS} = 200V, I_D = 3.4A, R_G = 25\Omega$	-	12		ns
Rise Time	$t_r$		-	25		
Turn-Off Delay Time	$t_{d(off)}$		-	20		
Fall Time	$t_f$		-	30		
<b>Drain-Source Body Diode Characteristics</b>						
Maximum Continuous Drain to Source Diode Forward Current	$I_S$		-	3.4	-	A
Source-Drain Diode Forward Voltage	$V_{SD}$	$I_S = 3.4A, V_{GS} = 0V$	-		1.4	V
Body Diode Reverse Recovery Time	$t_{rr}$	$I_F = 3.4A, di/dt = 100A/\mu s$	-	200		ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	1.0		$\mu C$

Note :

1. Pulse width is based on  $R_{\theta JC}$  &  $R_{\theta JA}$  and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ , pulse width limited by junction temperature  $T_J(MAX)=150^\circ C$ .
3.  $I_{SD} \leq 3.4A$ ,  $di/dt \leq 200A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J=25^\circ C$
4.  $L=25.8mH$ ,  $I_{AS}=3.4A$ ,  $V_{DD}=50V$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ C$

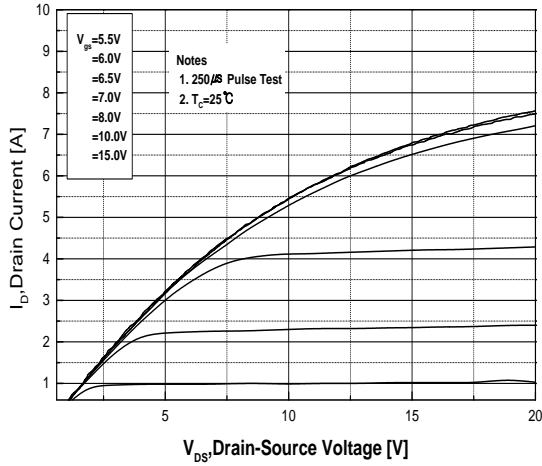


Fig.1 On-Region Characteristics

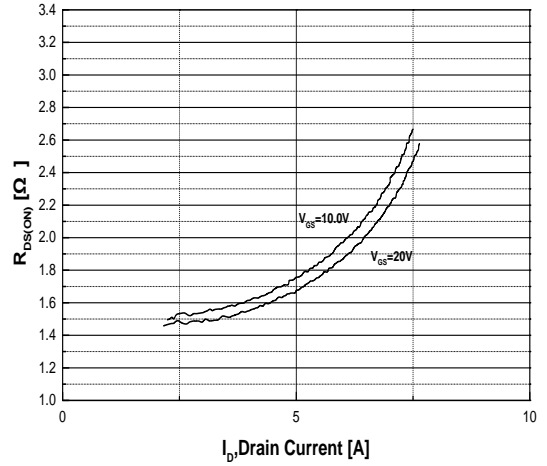


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

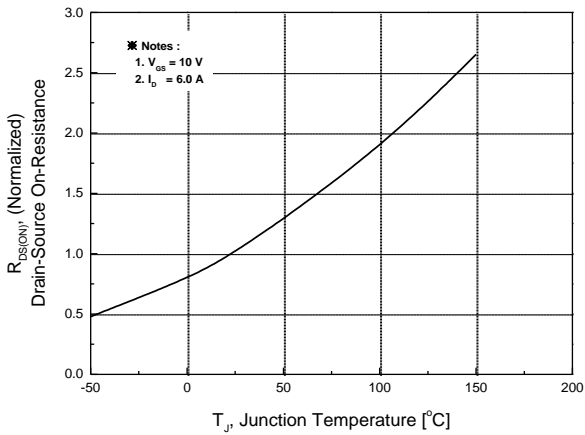


Fig.3 On-Resistance Variation with Temperature

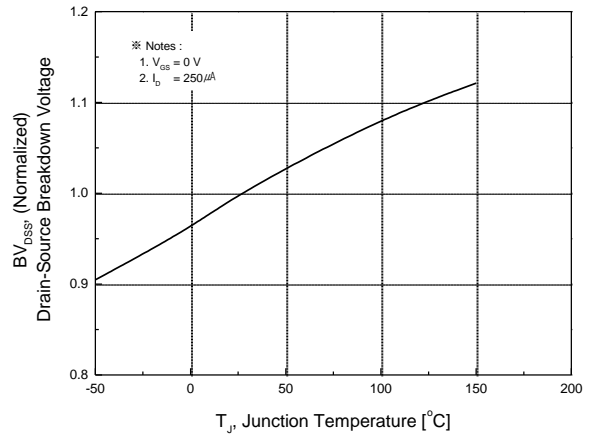


Fig.4 Breakdown Voltage Variation vs. Temperature

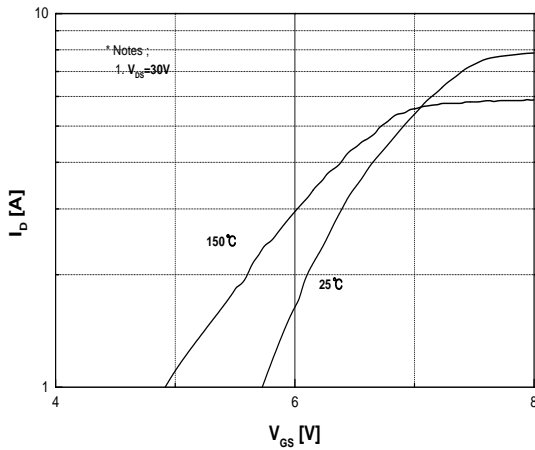


Fig.5 Transfer Characteristics

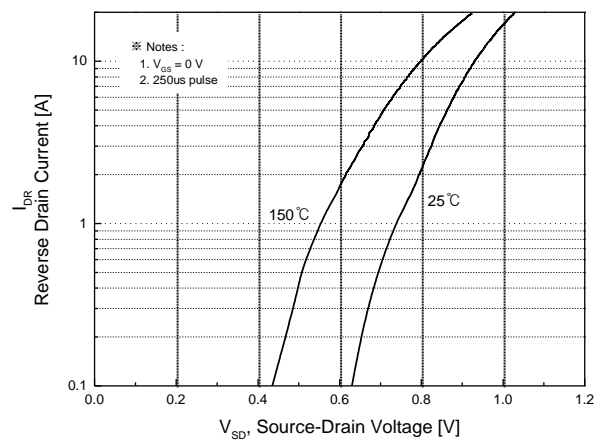
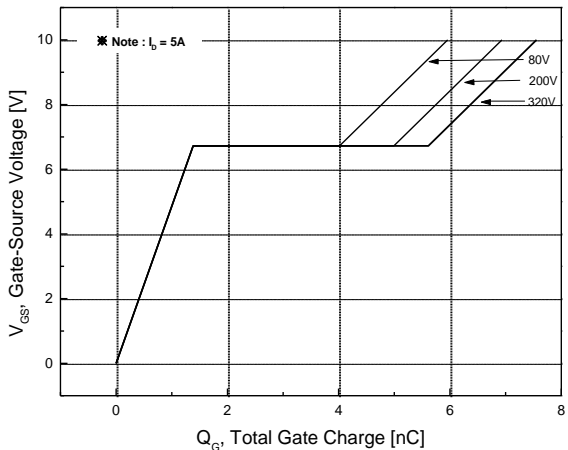
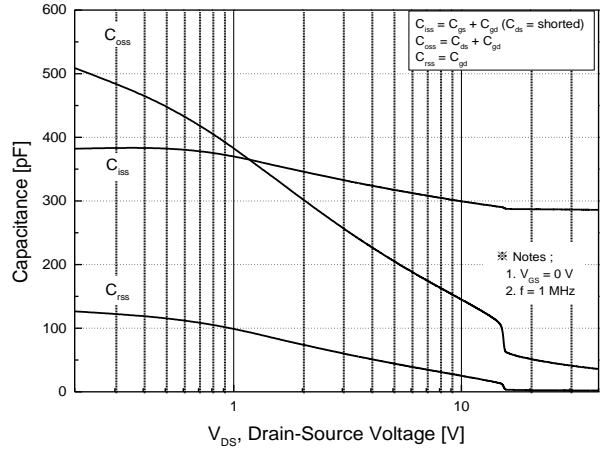


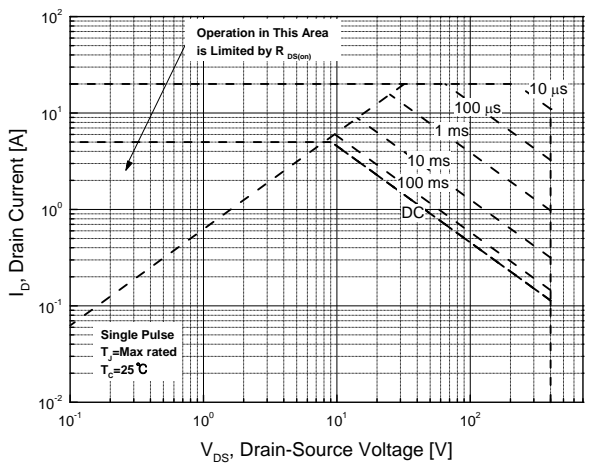
Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature



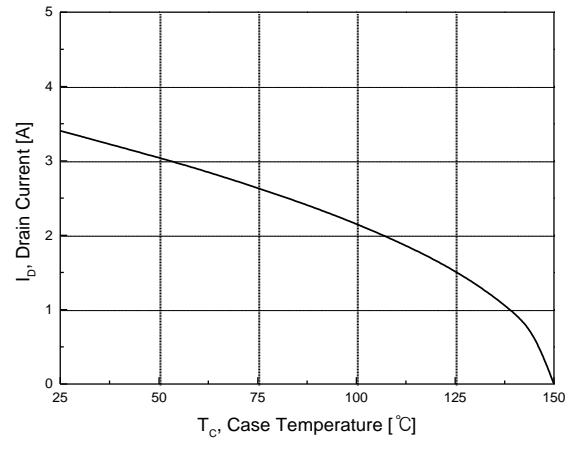
**Fig.7 Gate Charge Characteristics**



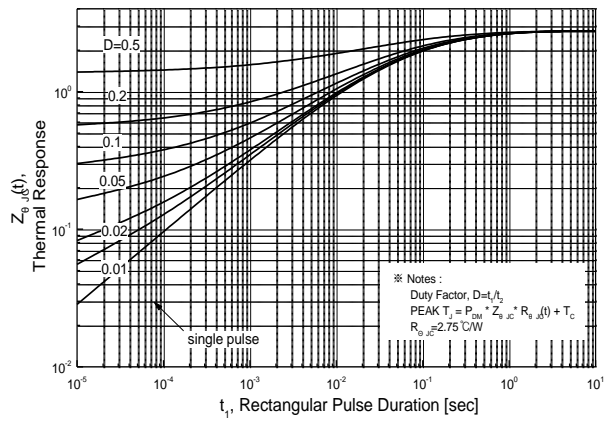
**Fig.8 Capacitance Characteristics**



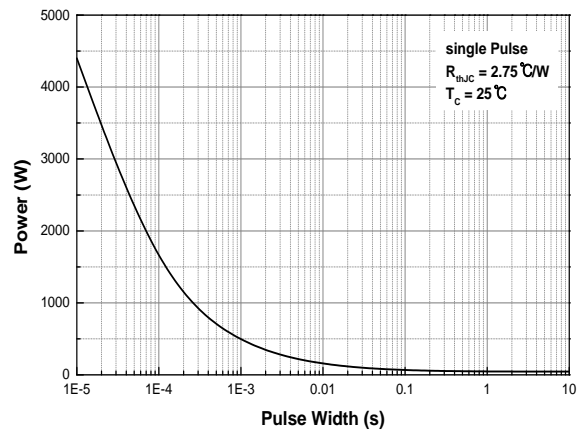
**Fig.9 Maximum Safe Operating Area**



**Fig.10 Maximum Drain Current vs. Case Temperature**



**Fig.11 Transient Thermal Response Curve**

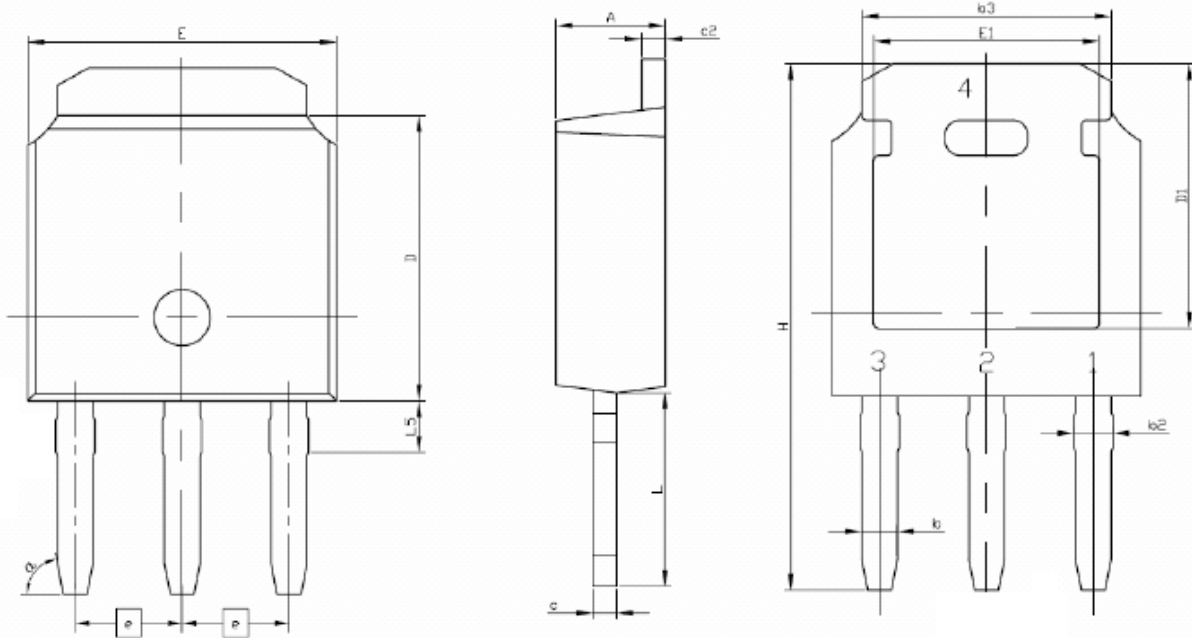


**Fig.12 Single Pulse Maximum Power Dissipation**

**Physical Dimension**

**TO-251-VS (IPAK-VS)**


Dimensions are in millimeters, unless otherwise specified



Symbol	MILLIMETERS	
	Minimum	Maximum
A	2.18	2.39
b	0.64	0.89
b2	0.76	1.14
b3	4.95	5.46
c	0.40	0.61
c2	0.40	0.61
D	5.97	6.223
D1	5.10	-
e	2.286 BSC	
E	6.35	6.73
E1	4.32	-
H	10.26	11.45
L	3.98	4.28
L5	-	1.23

**DISCLAIMER:**

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